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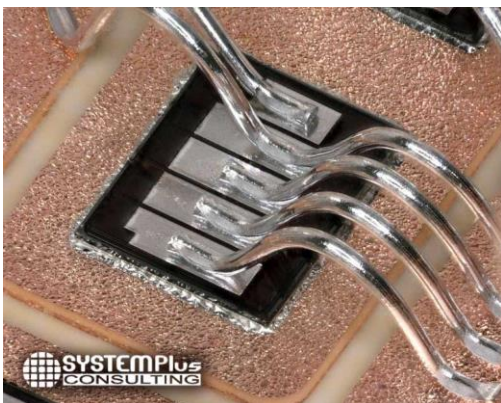
POWER

DISPLAY

Structure, Process & Cost Analysis

1200V CoolSiC™ MOSFET Module DF11MR12W1M1_B11, from Infineon

Infineon expands its presence in the SiC market with a new 1200V SiC MOSFET-based boost converter for solar applications



The market outlook for SiC devices is promising, with a compound annual growth rate (CAGR) of 28% from 2016 - 2020. This will increase to 40% from 2020 - 2022 due to growth in industrial applications. In total, the SiC market will exceed \$1B in 2022. In the photovoltaic sector, SiC devices have an actual value of \$71M, which will increase by around 28% in 2022. The reason for this relates to market forces pushing for loss reduction, not only for

the sake of improved efficiency but also for smaller packages.

Capitalizing on Infineon's years of experience and know-how, the CoolSiC™ MOSFET product line enables drastically new system designs compared to the usual silicon-based converters. Infineon's new boost converter targets the entire photovoltaic conversion chain (inverter, battery charging, and energy storage). Based on a 1200V 23mΩ SiC Trench MOSFET, this product's best-in-class performance enables highly efficient energy harvesting.

Supported by a full teardown of the module's components and housing, this report reveals Infineon's innovative assets, such as its unique shifted doping implantation design, which brings several advantages to the 1200V SiC MOSFET: superior gate-oxide reliability, switching performance and conduction losses, the highest transconductance level (gain), a threshold voltage of $V_{th} = 4\text{ V}$, and short-circuit robustness.

Another of this module's assets is the use of cutting-edge SiC Schottky Diodes from Infineon's thinQ!™ product line. This component is based on an MPS (merged-pin-Schottky) structure that combines the shielding of the electric field from the Schottky barrier and an increased surge current capability via hole injection.

Title: Infineon DF11MR12W1M1_B11 1200V CoolSiC MOSFET Module
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COMPLETE TEARDOWN WITH:

- Detailed photos
- Precise measurements
- Materials analysis
- Manufacturing process flow
- Supply chain evaluation
- Manufacturing cost analysis
- Estimated sales price
- Comparison with Infineon's Si IGBT module packaging
- Comparison with Rohm's SiC module packaging
- Comparison with competitors' 1200V SiC MOSFETs

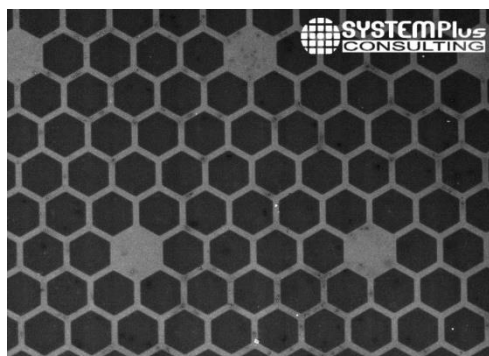
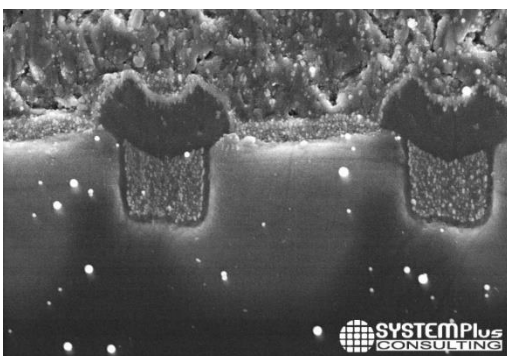


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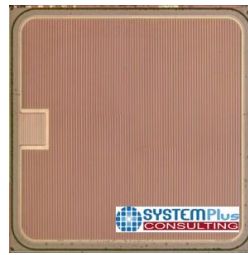
1200V SiC MOSFET vs Silicon IGBT: Technology and Cost comparison

New SiC MOSFET technologies are trying to compete with well-established silicon IGBTs, but will they succeed?



STMicroelectronics 1200V SiC MOSFET STC30N120

The 1st generation 1200V SiC MOSFET device from STMicroelectronics has good current density at a very competitive cost.



ROHM 1700V SiC MOSFET SCT2H12NZGC11 Discrete

In its new series of SiC MOSFETs, Rohm uses trench structures for 650V and 1200V products, while 1700V products use planar structures.



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